MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

CSP64 6.278x6.648
CASE 570BJ
ISSUE A

DATE 10 SEP 2019

NOTES:
2. CONTROLLING DIMENSION: MILLIMETERS [mm].
3. SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C: THEimators PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. GLASS: 0.400 [mm] THICKNESS, REFRACTIVE INDEX = 1.52.
7. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.0241 THICKNESS.
8. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
9. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUM A AND B IS ±0.1°.
10. REFER TO THE DEVICE DATA SHEET FOR TOTAL POLE ARRAY DEFINITIONS.
11. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (0.014, 0.12).
12. PACKAGE CENTER (X, Y) = (0.000, 0.000).

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